504421309 06/20/2017

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHUNPEI YAMAZAKI	05/31/2017
YOSHINORI YAMADA	06/01/2017
MASASHI OOTA	06/01/2017

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD
Street Address:	398, HASE
City:	ATSUGI-SHI, KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15537915

CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided: if that is unsuccessful, it will be sent via US Mail.

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202) 783-5070
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ATTORNEY DOCKET NUMBER: 12732-1840US1

NAME OF SUBMITTER: SHELLEY M. TAYLOR

SIGNATURE: /Shelley M. Taylor/

DATE SIGNED: 06/20/2017

Total Attachments: 1

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PATENT 504421309 REEL: 042754 FRAME: 0935

ASSIGNMENT

For valuable consideration, We, <u>Shunpei YAMAZAKI of Setagaya</u>, <u>Tokyo, Japan, Yoshinori YAMADA of Isehara, Kanagawa, Japan and Masashi OOTA of Atsugi, Kanagawa, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a <u>Japanese</u> corporation having a place of business at:</u>

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and
interest throughout the world in the inventions and improvements which are subject of an application for
United States Patent signed by us this day, entitled METHOD FOR MANUFACTURING SPUTTERING
TARGET, filed June 20, 2017 , and assigned U.S. Serial Number 15/537,915 , and
we authorize and request the attorneys appointed in said application to hereafter complete this assignment by
inserting above the filing date and serial number of said application when known; this assignment including
said application, any and all United States and foreign patents, utility models, and design registrations
granted for any of said inventions or improvements, and the right to claim priority based on the filing date of
said application under the International Convention for the Protection of Industrial Property, the Patent
Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we
authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models,
design registrations and like rights of exclusion and for inventors' certificates for said inventions and
improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns,
without further compensation to perform such lawful acts and to sign such further applications, assignments,
Preliminary Statements and other lawful documents as the Assignce may reasonably request to effectuate
fully this assignment.

Signature	Sliga Boggler
Name:	Shunpei YAMAZAKI
Date:	05/3/ /2017
Signature Name: Date:	Yoshinori YAMADA Yoshinori YAMADA 86/01/2017
Signature	Masashi Dofa
Name:	Masashi OOTA
Date:	06/01/2017

RECORDED: 06/20/2017

PATENT REEL: 042754 FRAME: 0936